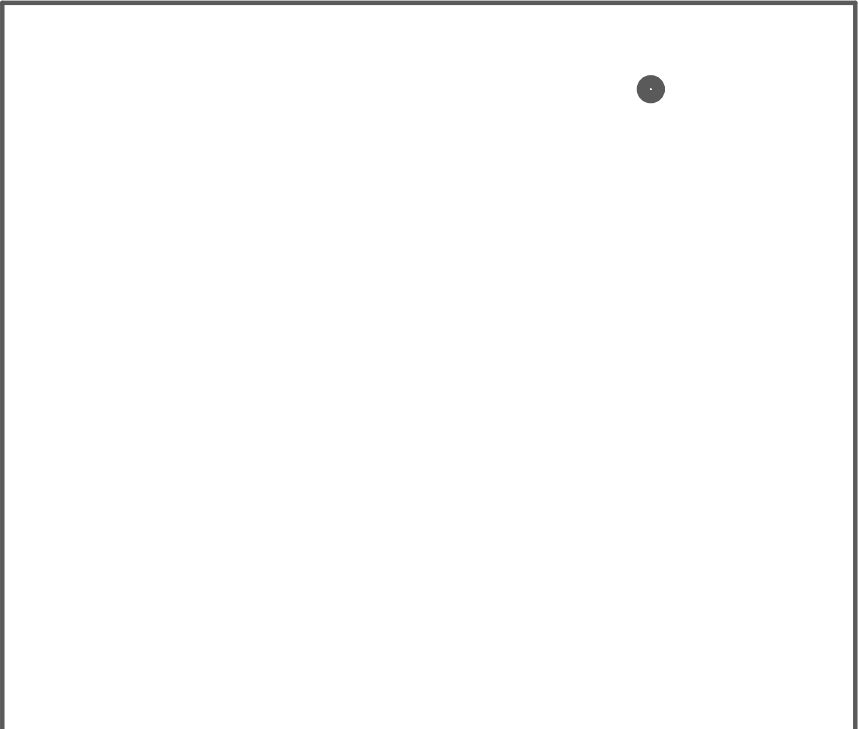


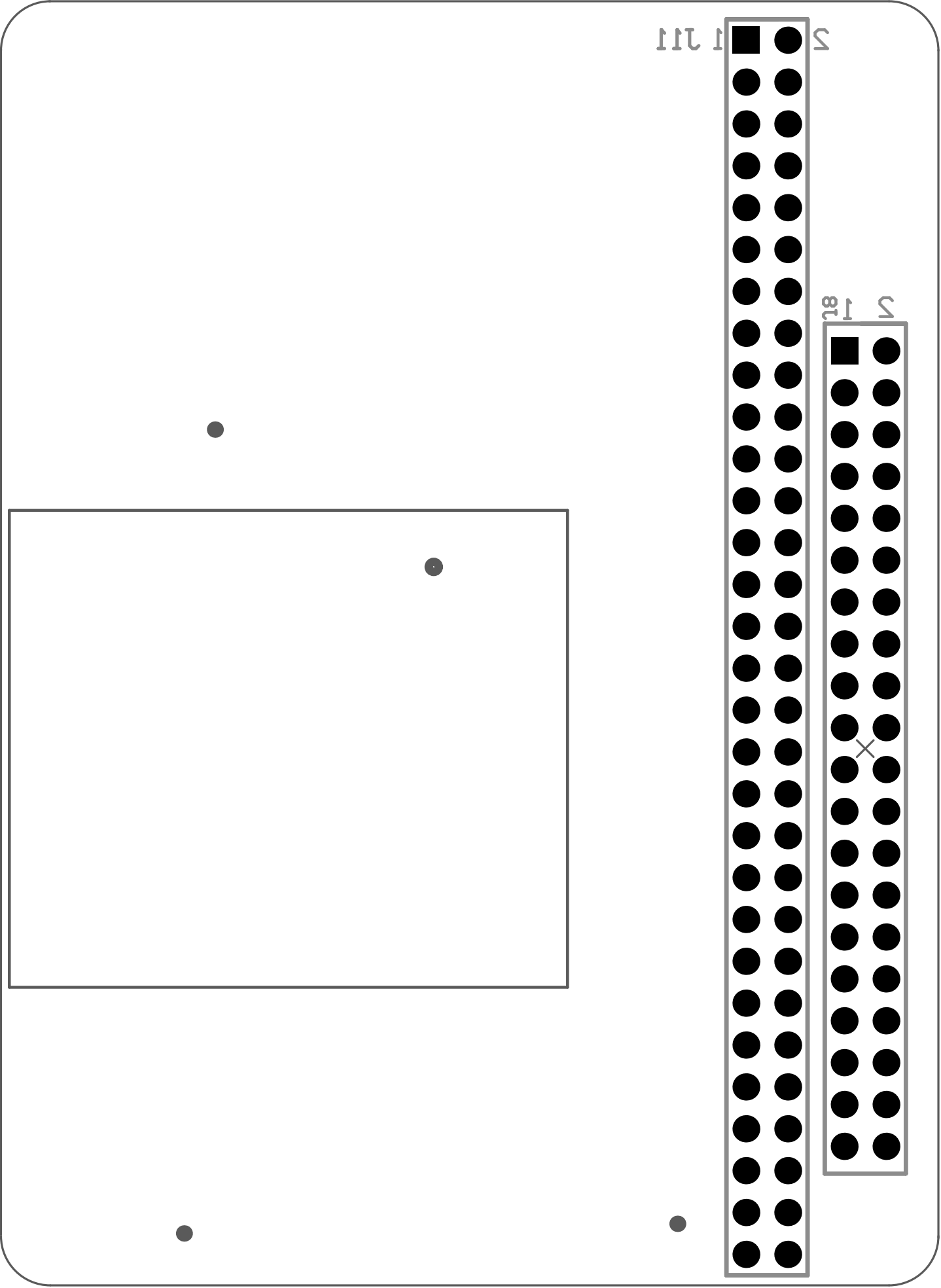
S 18

X












X

1111





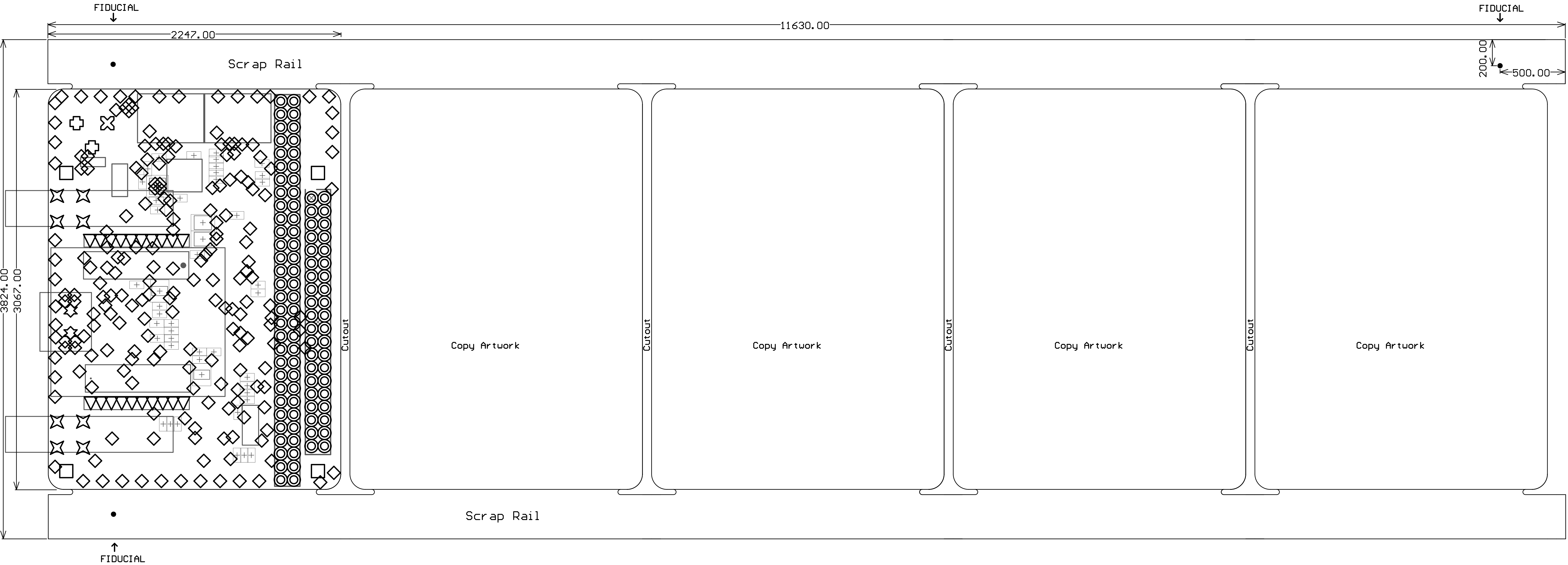
Board Stack Report

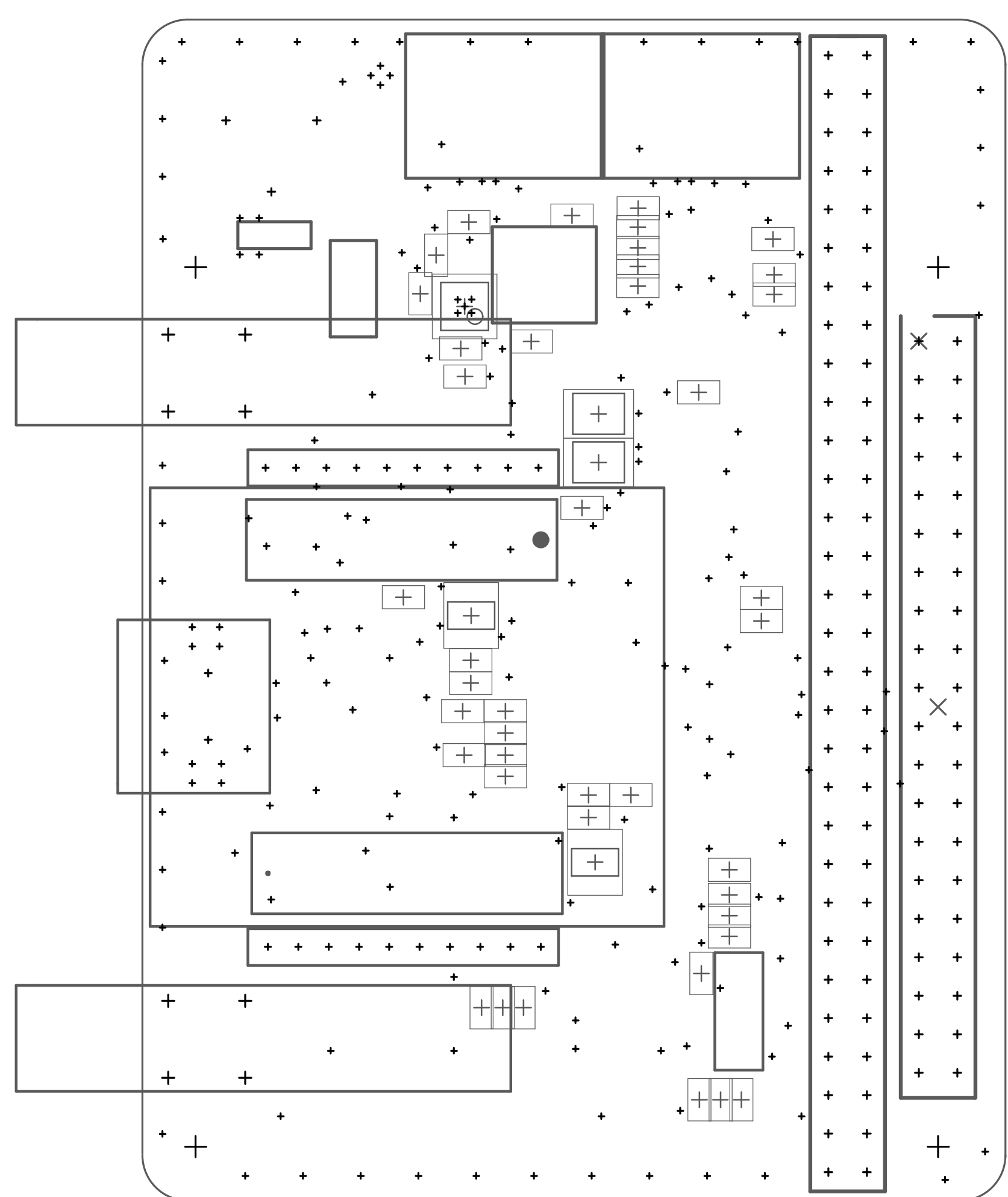
Stack Up		Layer Stack		
Layer	Board Layer Stack	Name	Material	Thickness
1		Top Paste		
2		Top Overlay		
3		Top Solder	Solder Resist	0.40mil
4		Top Layer	Copper	1.37mil
5		Dielectric 1	FR-4	6.70mil
6		Internal Plane 1	Copper	1.37mil
7		Dielectric 3		43.00mil
8		Internal Plane 2	Copper	1.37mil
9		Dielectric 2		6.70mil
10		Bottom Layer	Copper	1.37mil
11		Bottom Solder	Solder Resist	0.40mil
12		Bottom Overlay		
13		Bottom Paste		

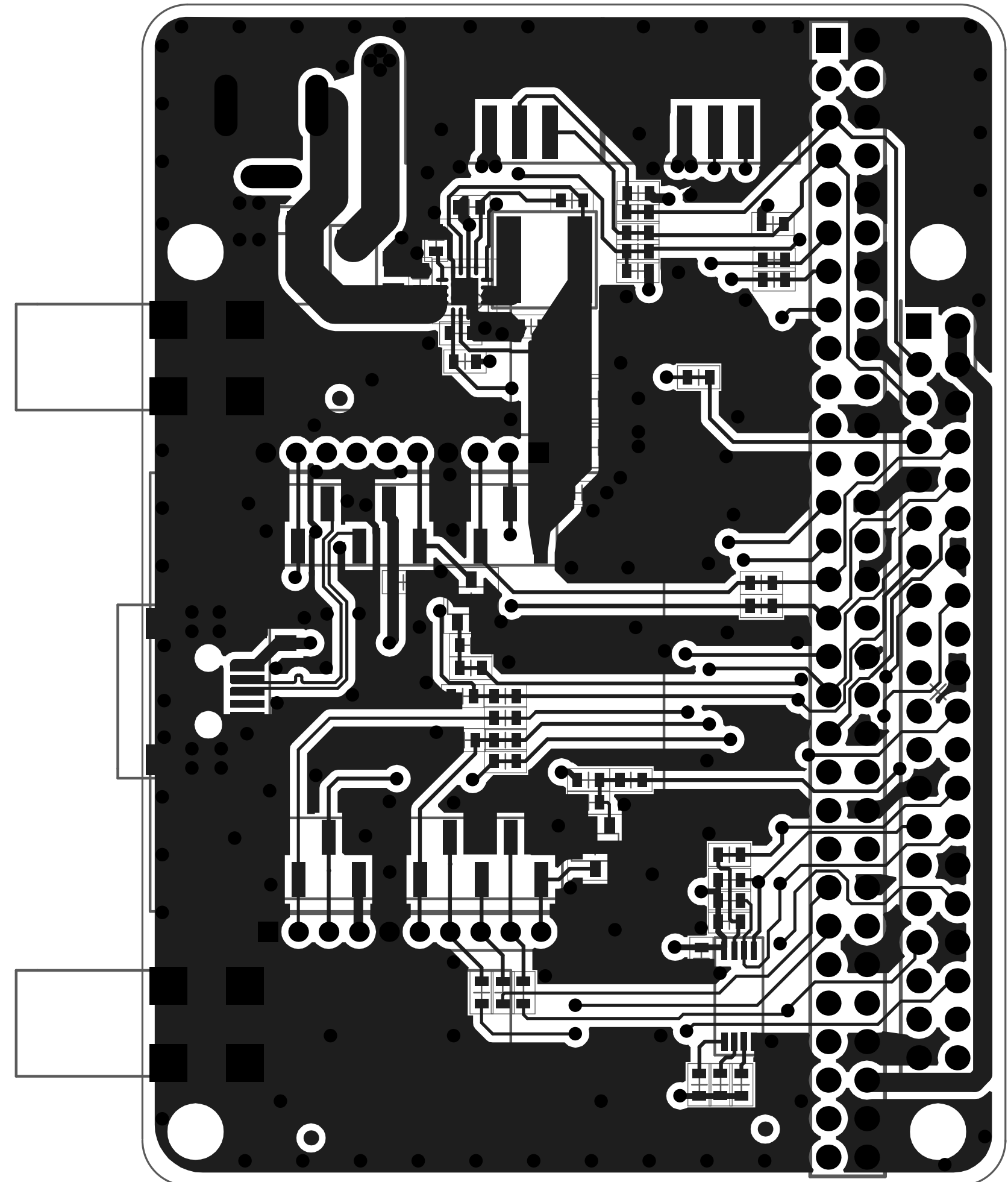
Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Top Layer	Copper	1.37mil		
4	Dielectric 1	FR-4	6.70mil	4.6	
5	Internal Plane 1	Copper	1.37mil		
6	Dielectric 3		43.00mil	4.6	
7	Internal Plane 2	Copper	1.37mil		
8	Dielectric 2		6.70mil	4.6	
9	Bottom Layer	Copper	1.37mil		
10	Bottom Solder	Solder Resist	0.40mil	3.5	
11	Bottom Overlay				

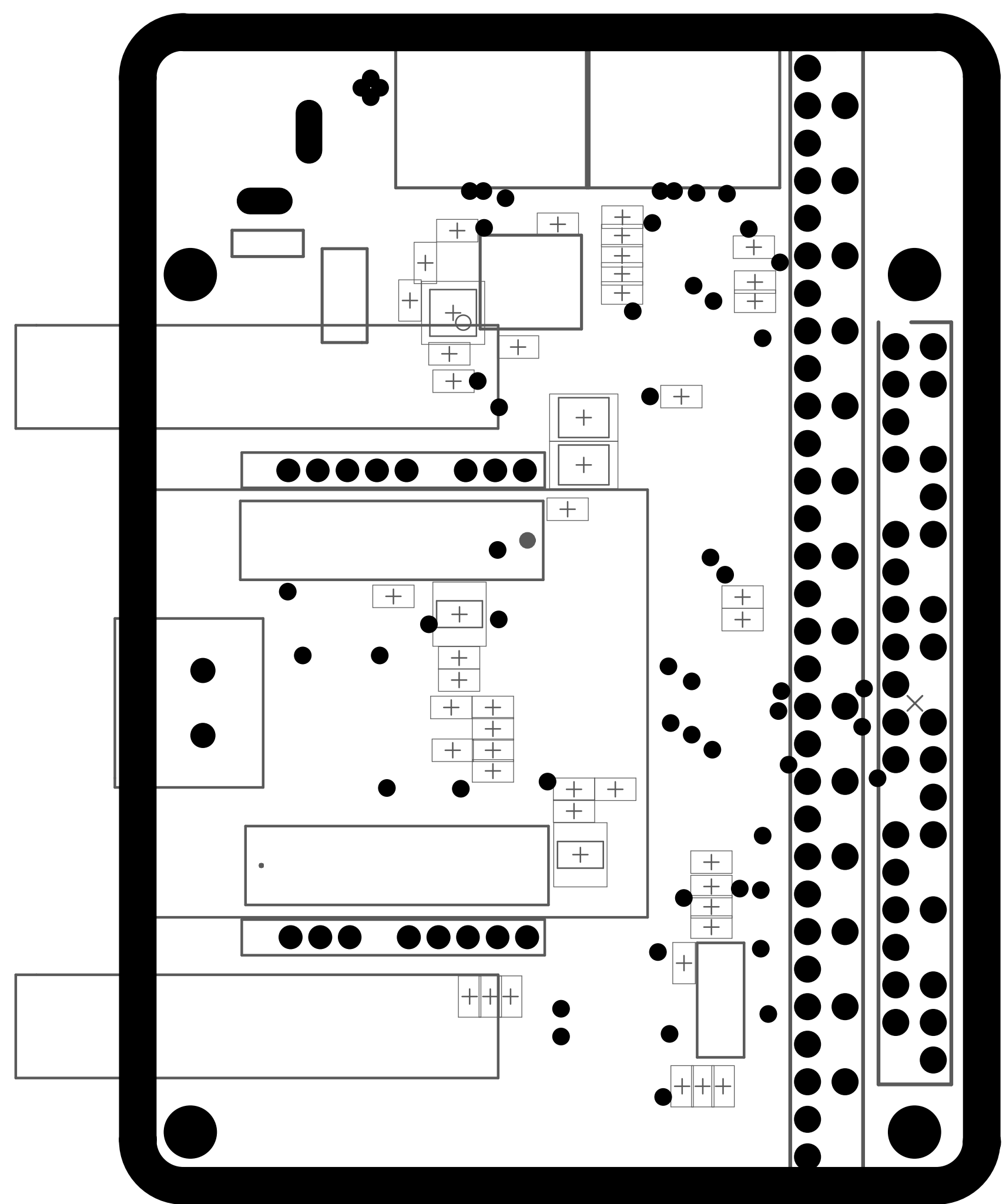
Symbol	Hit Count	Finished Hole Size	Plated	Hole Type
⊠	1	39.37mil (1.000mm)	PTH	Slot
✱	2	35.43mil (0.900mm)	NPTH	Round
⊕	2	39.37mil (1.000mm)	PTH	Slot
□	4	110.00mil (2.794mm)	NPTH	Round
⊠	8	65.00mil (1.651mm)	PTH	Round
▽	20	31.50mil (0.800mm)	PTH	Round
●	100	40.00mil (1.016mm)	PTH	Round
◇	202	15.00mil (0.381mm)	PTH	Round
	339 Total			

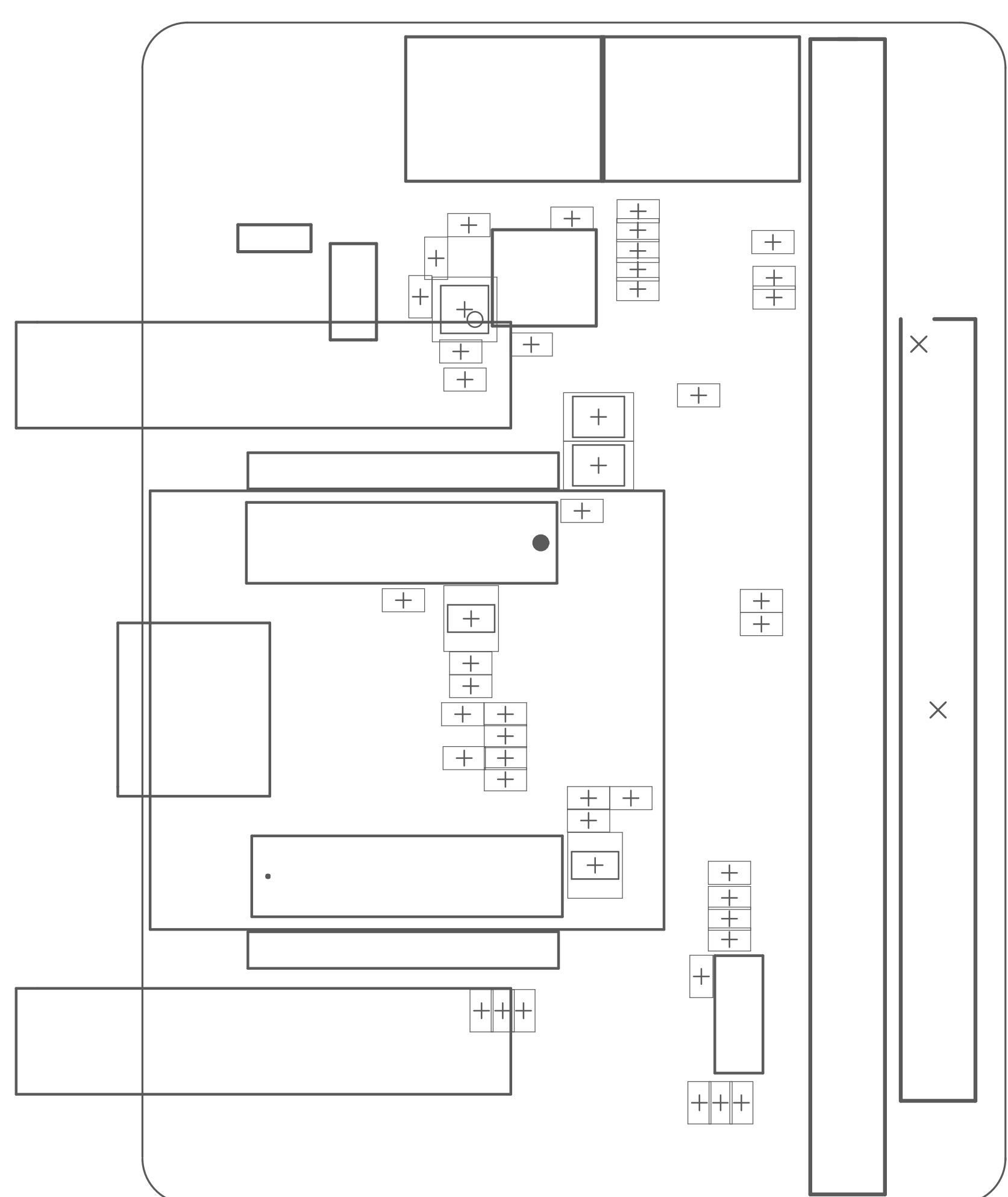
- NOTES:
1. BOARD IS A 5x1 ARRAY. SEE PANEL ARTWORK LAYER FOR PANEL DETAIL.
 2. BOARD TO BE SCORED AT DESIGNATED LINES. SCORING TO BE 30 DEG.
 3. BOARD TO USE Tg 170C OR GREATER
 4. BOARD THICKNESS TOLERANCE +/- 10%
 - 5) BOARD TO USE GREEN SOLDER MASK
 - 6) BOARD TO USE WHITE SILK SCREEN
 - 7) MIN HOLE WALL THICKNESS 1 mil
 - 8) BOARD TO USE ENIG SURFACE FINISH
 - 9) COPPER LAYERS TO BE 10Z COPPER

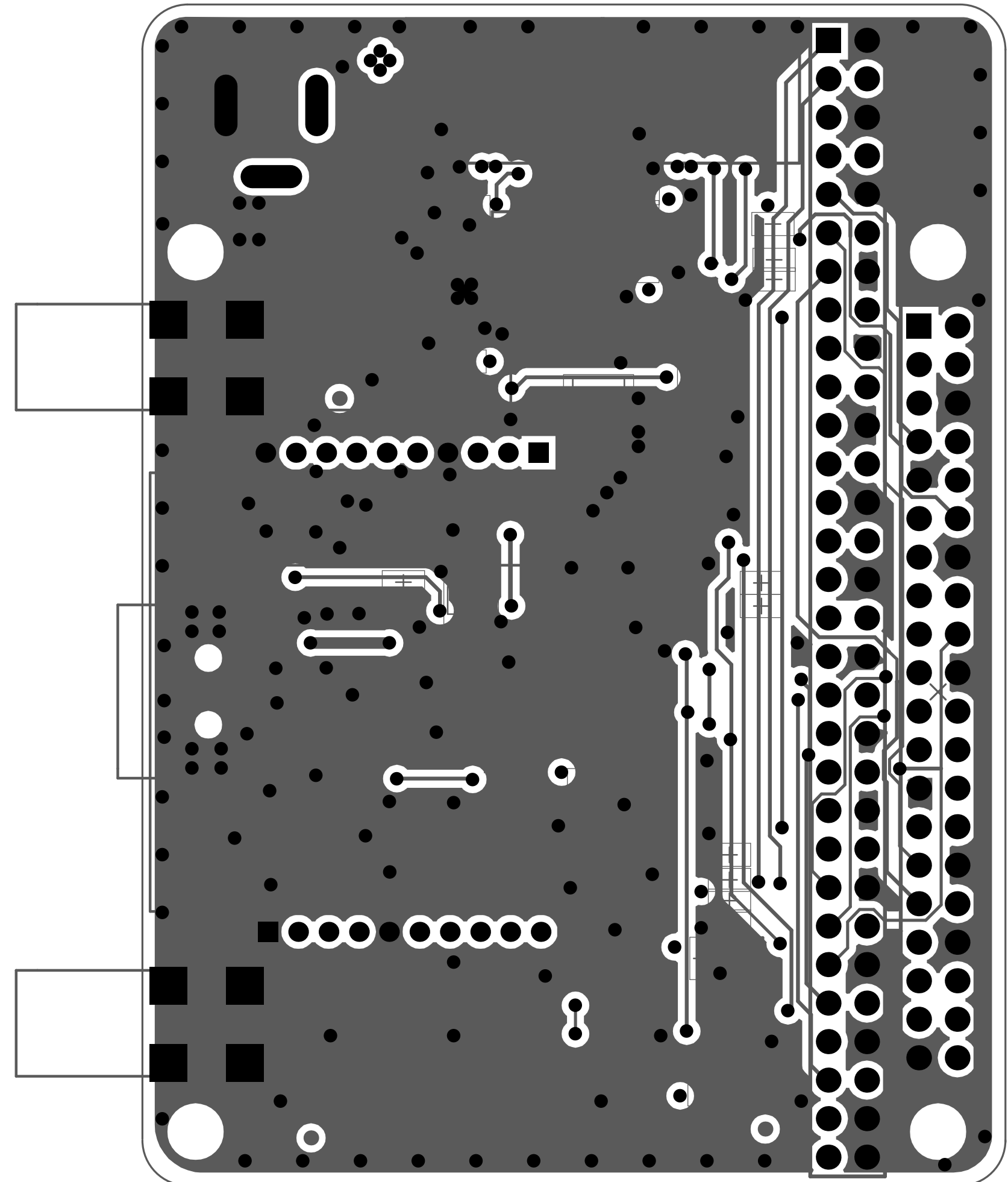


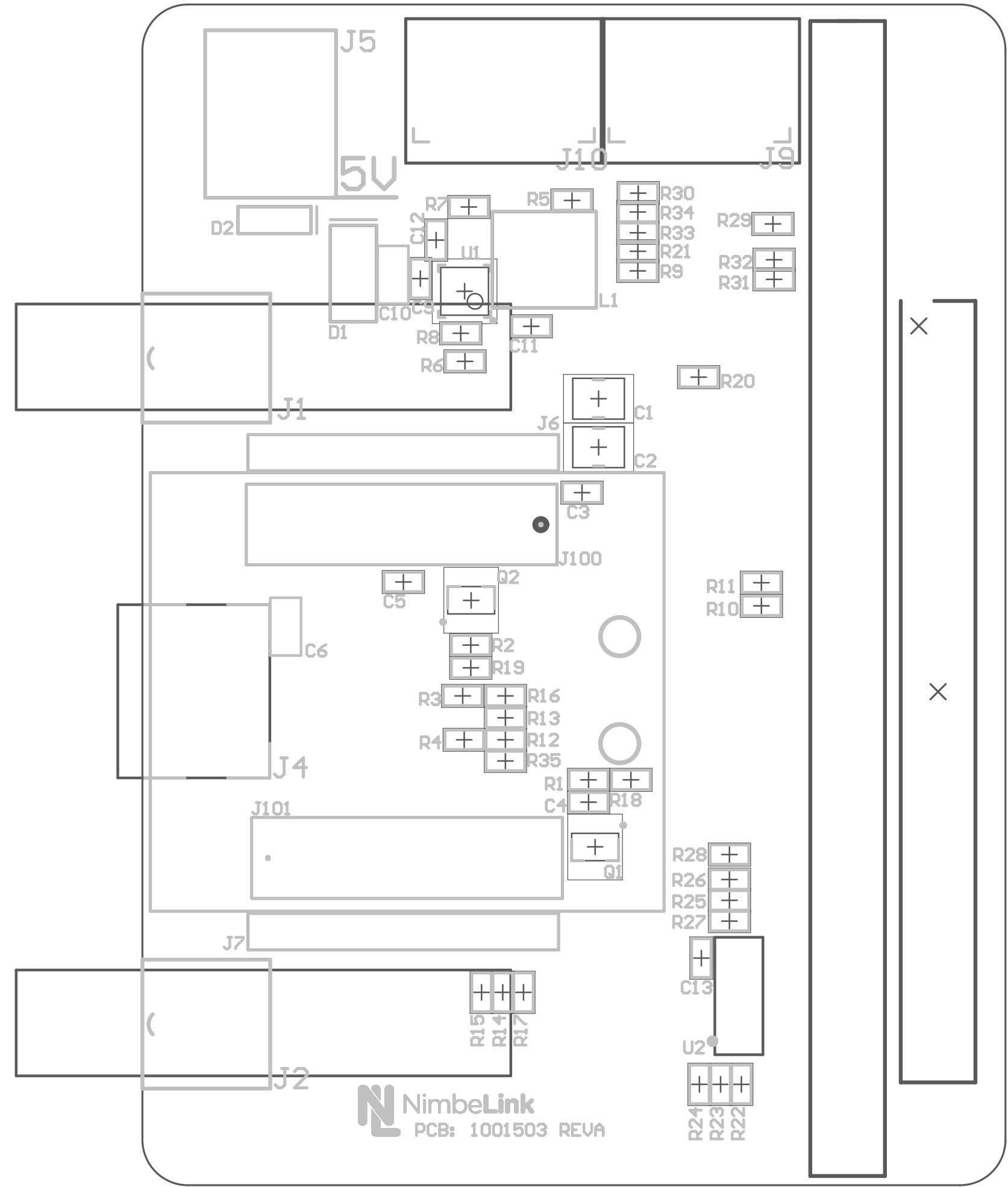


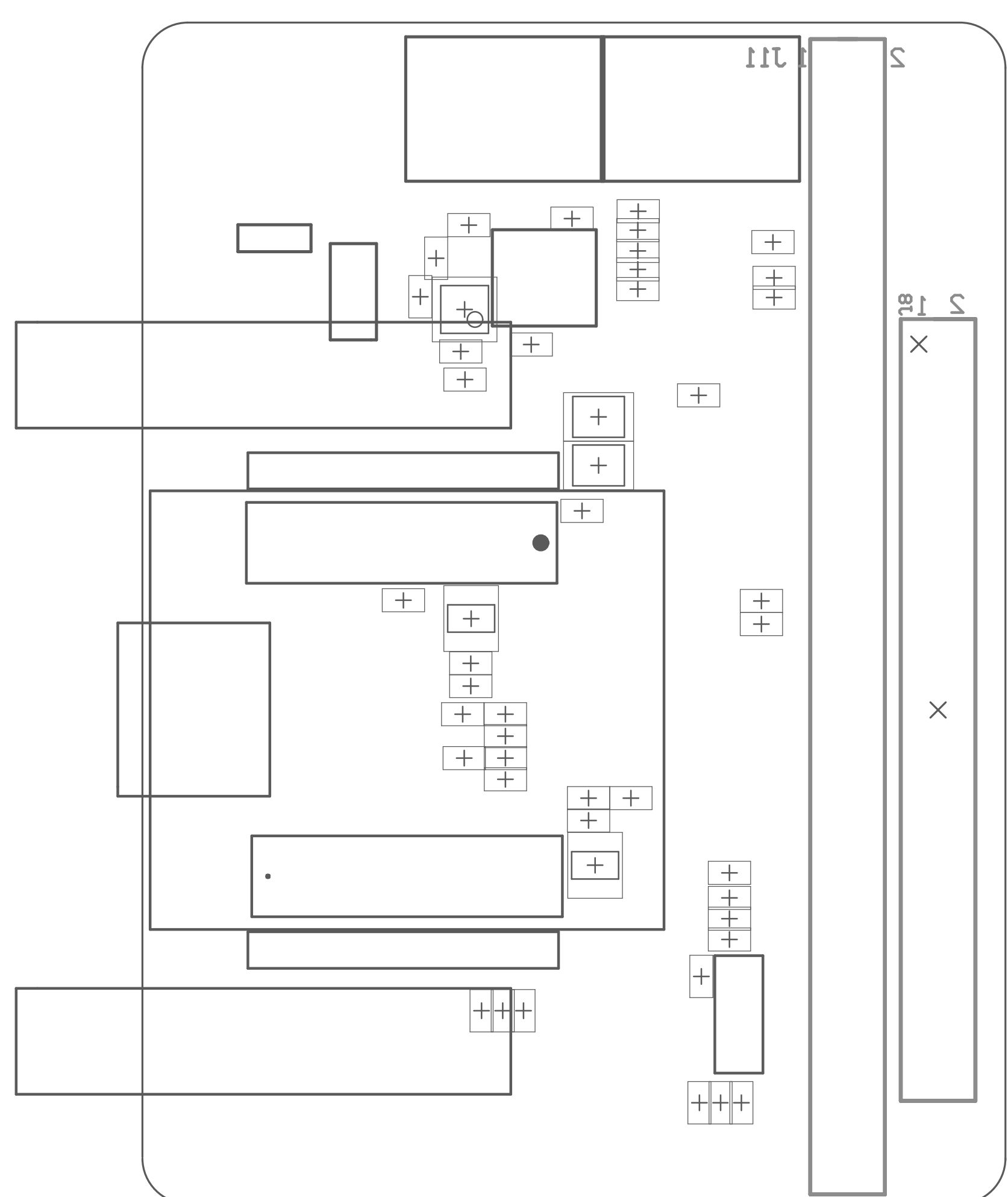


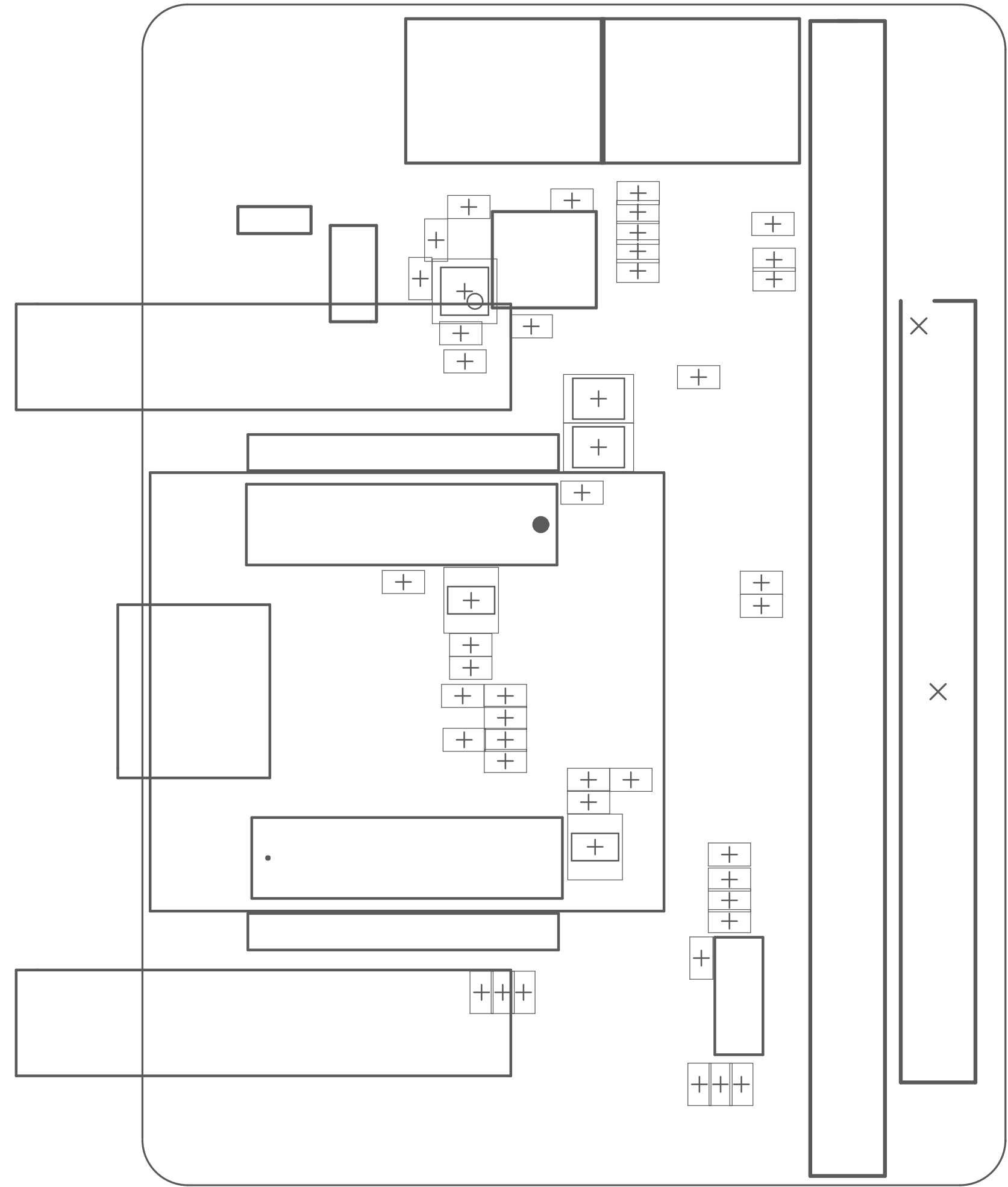


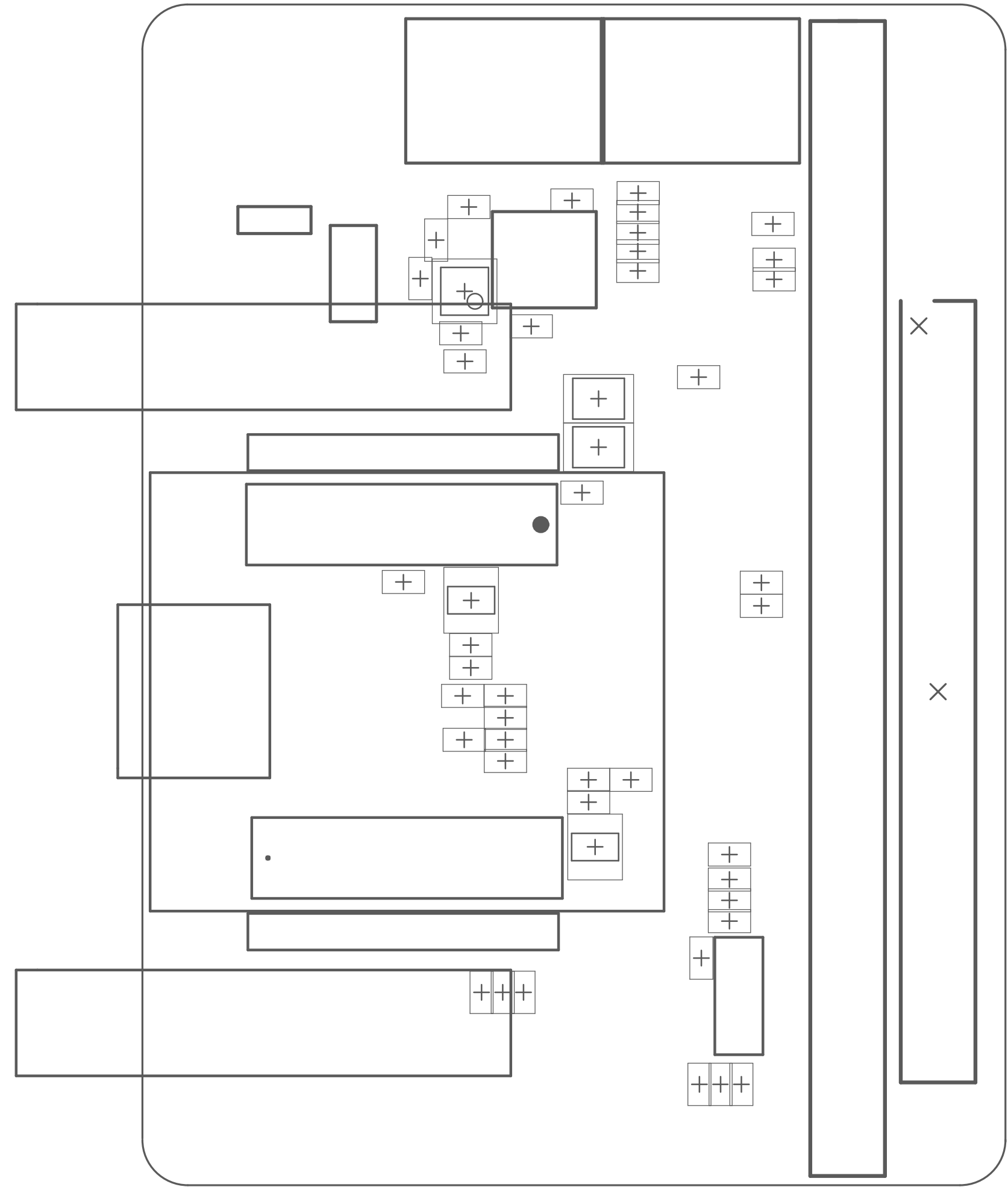


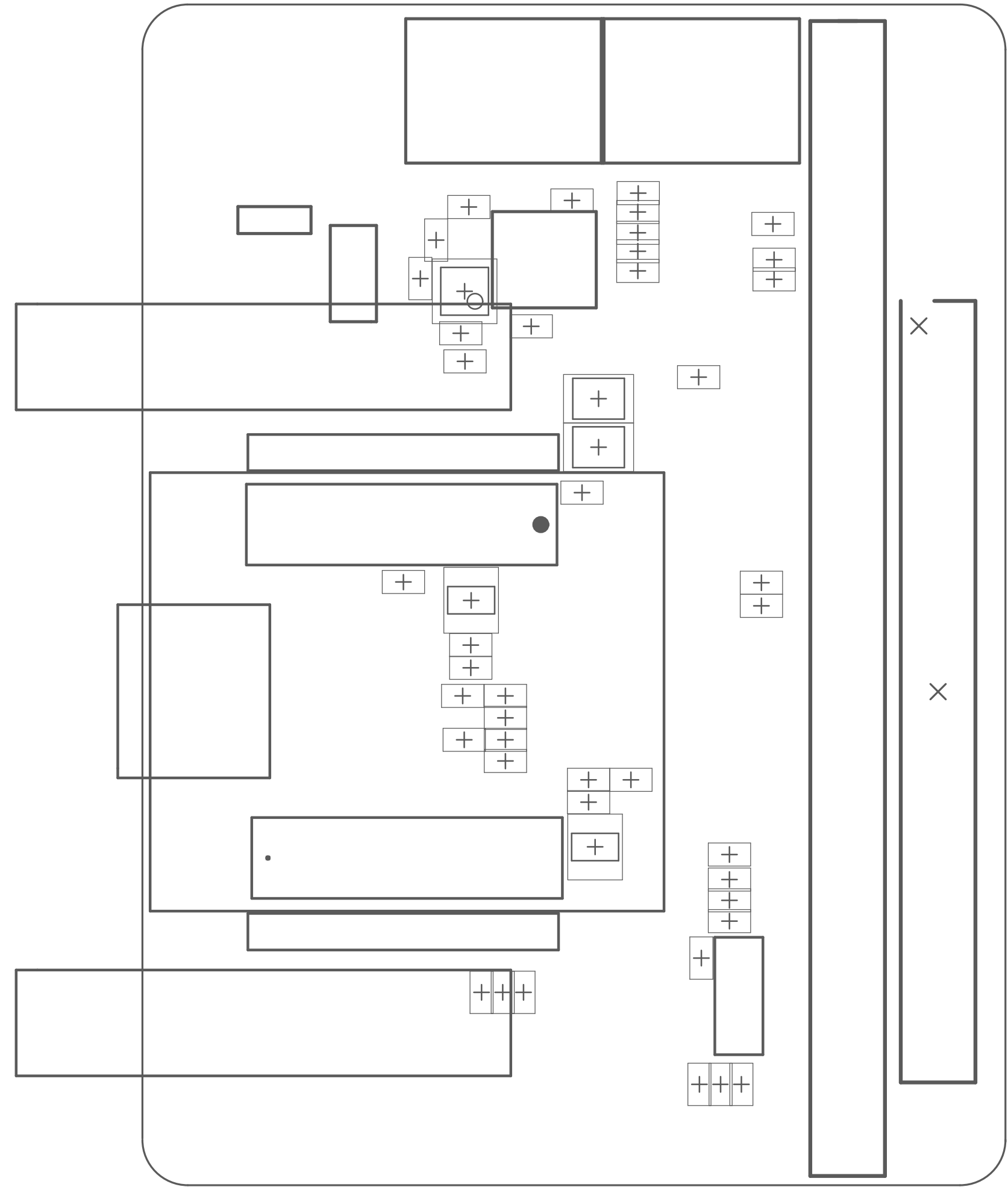


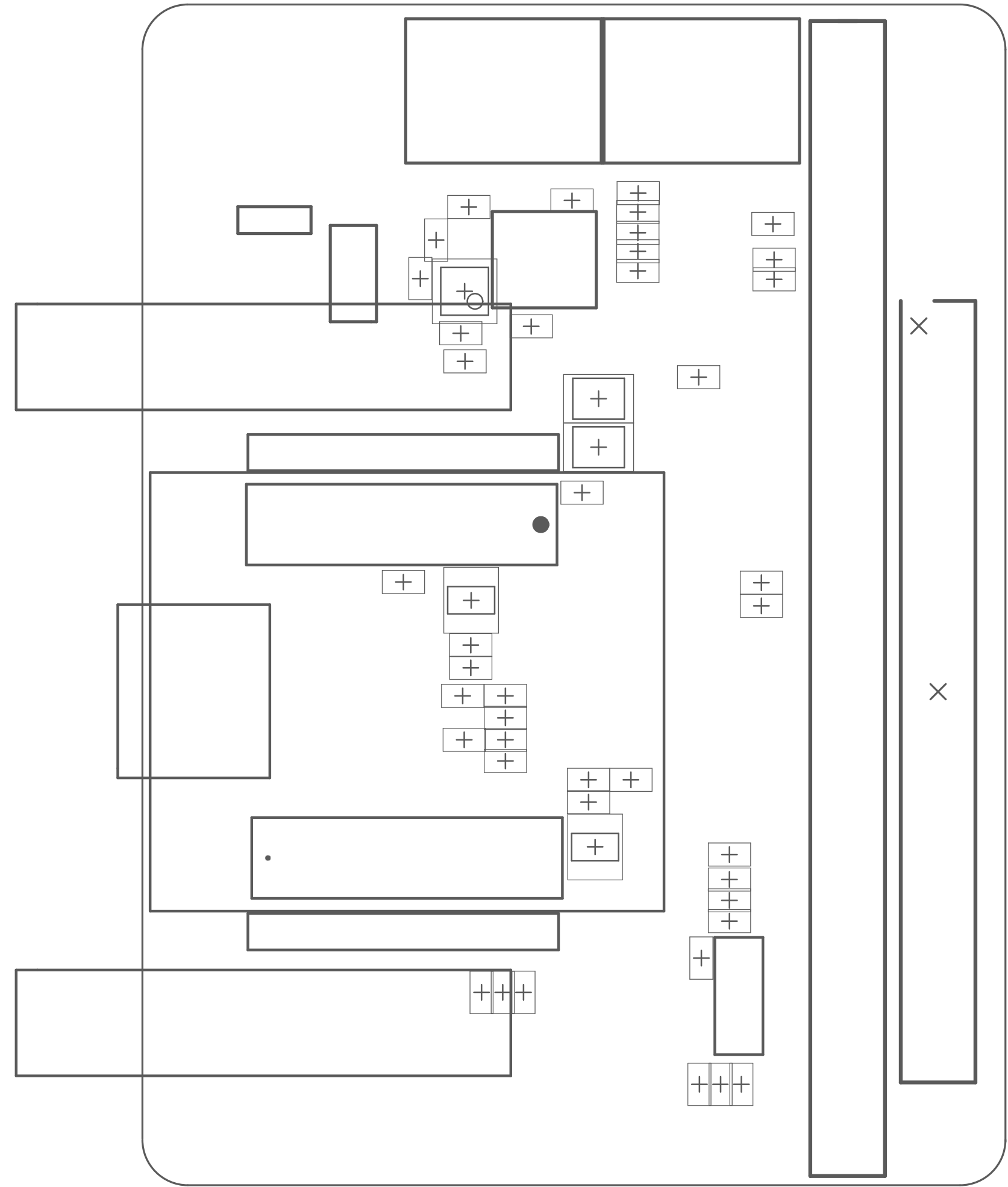


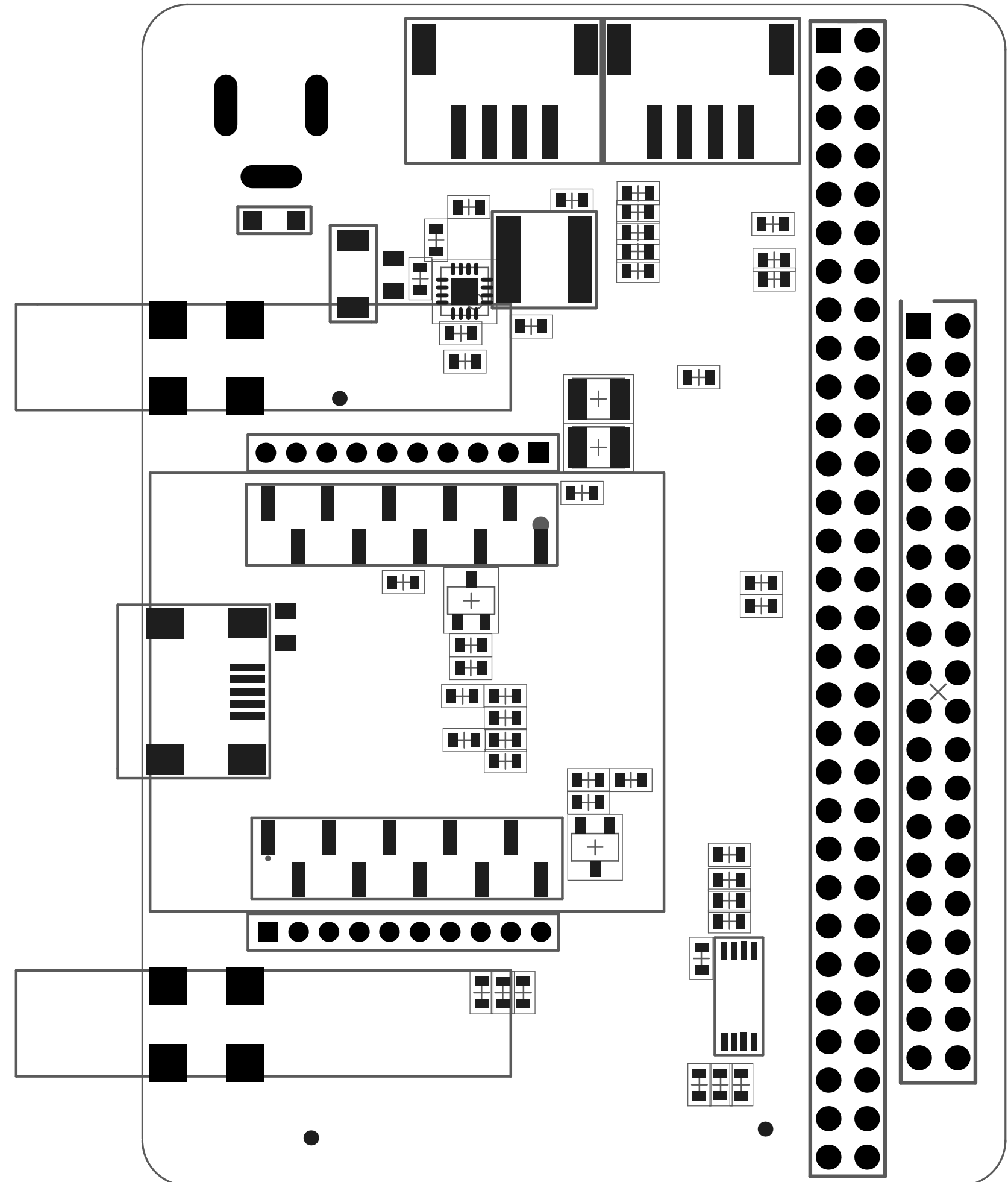


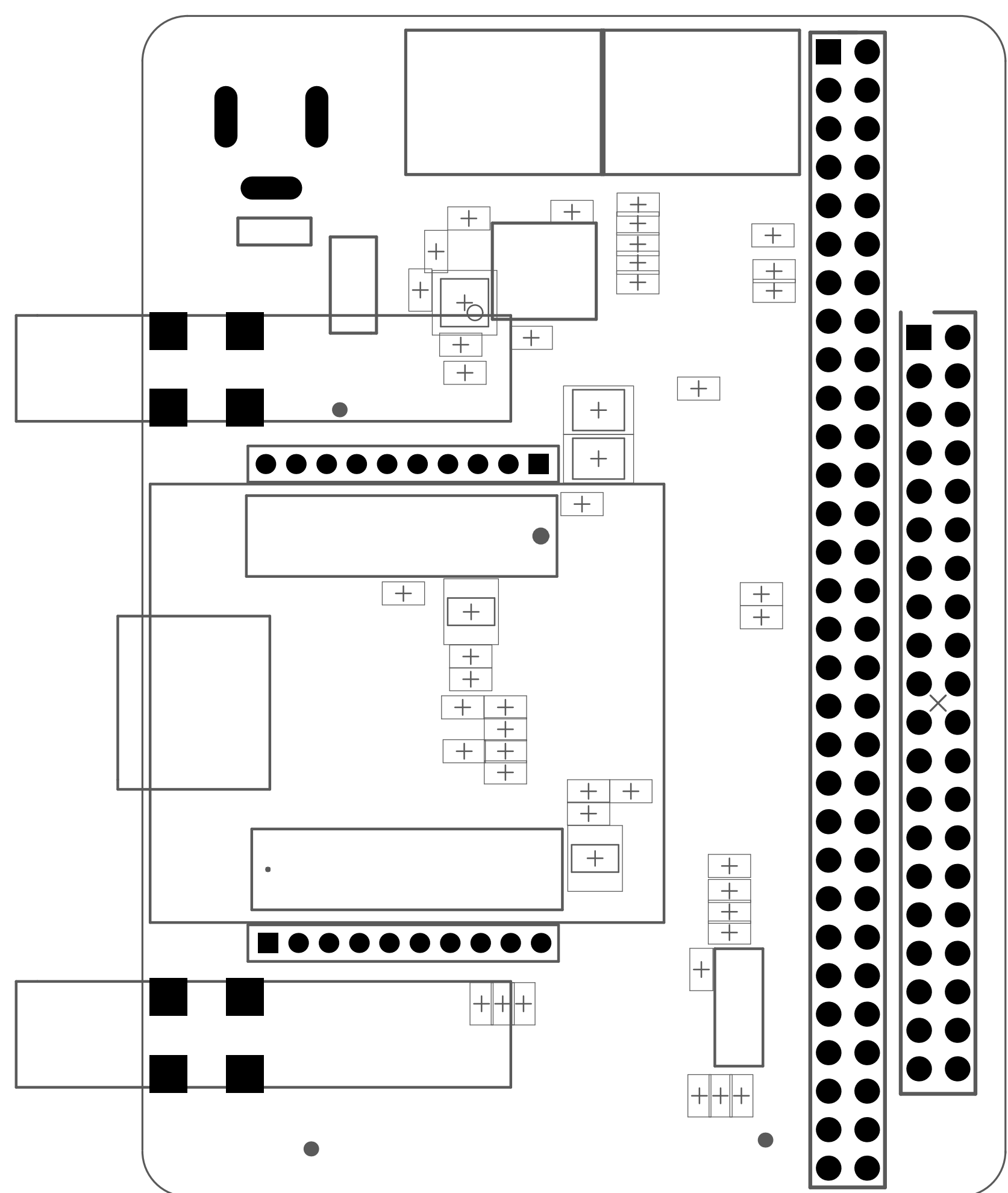


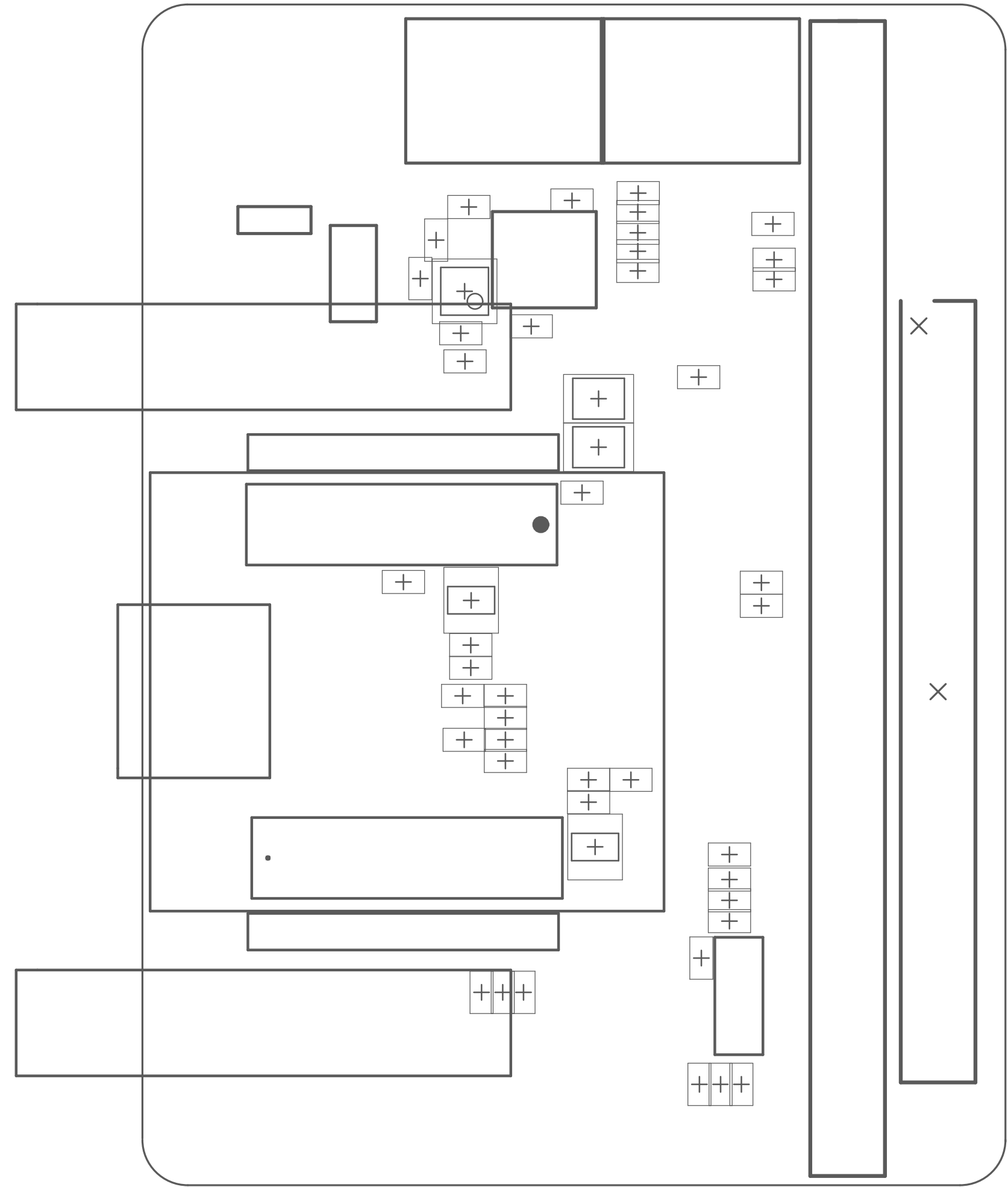












Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Top Layer	Copper	1.37mil		
4	Dielectric 1	FR-4	6.70mil	4.6	
5	Internal Plane 1	Copper	1.37mil		
6	Dielectric 3		43.00mil	4.6	
7	Internal Plane 2	Copper	1.37mil		
8	Dielectric 2		6.70mil	4.6	
9	Bottom Layer	Copper	1.37mil		
10	Bottom Solder	Solder Resist	0.40mil	3.5	
11	Bottom Overlay				

Symbol	Hit Count	Finished Hole Size	Plated	Hole Type
⊠	1	39.37mil (1.000mm)	PTH	Slot
✱	2	35.43mil (0.900mm)	NPTH	Round
⊕	2	39.37mil (1.000mm)	PTH	Slot
□	4	110.00mil (2.794mm)	NPTH	Round
⊠	8	65.00mil (1.651mm)	PTH	Round
▽	20	31.50mil (0.800mm)	PTH	Round
●	100	40.00mil (1.016mm)	PTH	Round
◇	202	15.00mil (0.381mm)	PTH	Round
	339 Total			

- NOTES:
1. BOARD IS A 5x1 ARRAY. SEE PANEL ARTWORK LAYER FOR PANEL DETAIL.
 2. BOARD TO BE SCORED AT DESIGNATED LINES. SCORING TO BE 30 DEG.
 3. BOARD TO USE Tg 170C OR GREATER
 4. BOARD THICKNESS TOLERANCE +/- 10%
 - 5) BOARD TO USE GREEN SOLDER MASK
 - 6) BOARD TO USE WHITE SILK SCREEN
 - 7) MIN HOLE WALL THICKNESS 1 mil
 - 8) BOARD TO USE ENIG SURFACE FINISH
 - 9) COPPER LAYERS TO BE 1OZ COPPER

